



Application form - Pact for Skills

Fields marked with * are mandatory.

Introduction

The Pact for Skills is a shared engagement and approach to skills development. It is firmly anchored in the principles of the [European Pillar of Social Rights](#) and supports the goals of the [Green Deal](#) and the [digital transformation](#), as set out in the Commission communication “[A strong Social Europe for Just Transitions](#)”.

The Pact aims to mobilise and incentivise private and public stakeholders to take concrete action for the **up skilling and reskilling of people of working age**, and, when relevant, pool efforts in the partnerships.

The Pact can be joint by any private or public organisation or partnership of organisations which aim to upskill or reskill people of working age.

The organisation(s) need(s) to be based in one of the Member States, EFTA or candidate countries.

Joining the Pact:

1. All stakeholders joining the Pact **sign up to the Charter** and its key principles, which they agree to respect and uphold.
2. Signatories of the Pact are invited to **translate their engagement into concrete commitments** on upskilling and reskilling. Commitments must be in line with the key principles and can be built around a number of “enablers” that illustrate concrete ways of implementing the different principles.
3. Commitments are monitored by at least one **key performance indicator**, e.g. number of people taking part in upskilling or reskilling.

Information on the organisation/partnership

* You apply:

- on your own (as one organisation)
- in partnership

*** Organisation/partnership name:**

IEEE Hungary and Romania Section, Electronic Packaging Society and Nanotechnology Council Joint Chapter
(IEEE Hu&Ro EPS&NTC Joint Chapter)

*** What type of stakeholder does your organisation represent?**

- Large employer (more than 250 employees) Employer's organisation (social partner) Research institution
- Micro, small or medium employer (up to 249 employees) Chamber of commerce, trade and crafts Non-governmental or civil society organisation
- Public authority (local, regional or national) Sectoral organisation Other
- Private or public employment services Training provider
- Trade union (social partner) Representative of an industrial cluster (member of a groups of specialised enterprises, often SMEs, and other related supporting actors in a location that cooperate closely)

Please specify:

Chapter of the IEEE Scientific Society

*** Country/ies in which the organisation/partnership operates:**

Hungary

Romania

*** Contact person(s), title(s):**

Attila Bonyâr Chapter Chair, Olivér Krammer Hungarian Contact, Radu Gabriel Bozomitu Romanian Contact

*** Email to contact person:**

krammer@ett.bme.hu

Website of the organisation/partnership:

site.ieee.org/huro-epsntc

Logo of the organisation/partnership:

The maximum file size is 1 MB.

The logo will be presented on the webpage together with the commitment.

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*** Please indicate in what sector(s) your organisation/partnership operates:**

- | | | |
|---|---|---|
| <input type="checkbox"/> Aerospace and Defence | <input checked="" type="checkbox"/> Electronics | <input type="checkbox"/> Proximity and Social Economy |
| <input type="checkbox"/> Agri-Food | <input type="checkbox"/> Energy-Intensive Industries | <input type="checkbox"/> Renewable Energy |
| <input type="checkbox"/> Construction | <input type="checkbox"/> Health | <input type="checkbox"/> Retail |
| <input type="checkbox"/> Creative and Cultural Industries | <input checked="" type="checkbox"/> Mobility-Transport-Automotive | <input type="checkbox"/> Textiles |
| <input type="checkbox"/> Digital | <input type="checkbox"/> N/A | <input type="checkbox"/> Tourism |

*** Give a short description of your organisation/partnership**

1000 character(s) maximum

The IEEE Hungary & Romania Section EPS & NTC Joint Chapter aims to join forces of electronic packaging and nanotechnology activities of the members to advance technology for humanity. The IEEE Electronics Packaging Society is the leading international forum for scientists and engineers engaged in the research, design and development of microsystems packaging and manufacturing. Its objectives are scientific, engineering, and educational in character. Its field of Interest includes all aspects of packaging and integration of electrical, electronic, optoelectronic, biological, micromechanical and sensing components; addressing signal and power delivery, material aspects, thermal and structural design and reliability. Purpose of the Nanotechnology Council (NTC) is to advance and coordinate work in the field of Nanotechnology carried out throughout the IEEE. NTC supports the theory, design, and development of nanotechnology and its scientific, engineering, and industrial applications.

Signing up to the Charter

Please confirm your organisation/partnership subscribes to the [Charter of the Pact for Skills](#), understand and share the principles of quality upskilling and reskilling. Signature of the Charter does not constitute an endorsement of the signatory organisation and its activities by the European Commission.

Commitment

*** Would you like to join the Pact with concrete commitment?**

Commitment is a concrete action (set of actions), which aims to upskill or reskill people of working age. In the file you can find a [non-exhaustive list of actions](#) that could be implemented under the Pact for Skills.

- Yes
 No

Non-exhaustive list of actions that could be implemented under the Pact for Skills.

[Non-exhaustive list of actions.pdf](#)

Please provide information on your commitment

If you have more than 5 actions under your commitment please contact us at EC-PACT-FOR-SKILLS@ec.europa.eu.

	Action in the commitment	Organisation/person/team responsible for implementation of the action	Target group of the action	How the implementation of the action will be monitored
1	TIE - Interconnection Techniques in Electronics	Prof. Norocel CODREANU, Politehnica University of Bucharest	The TIE contest is organized for BSc, MSc and PhD students by 12-15 Universities interested to participate in TIE. (For 10-40 students per university, a total ca. 300 students). The contest has two stages: (1) local stage, which takes place in each university; 2. final stage, which takes place in a university of different cities each year, selected by the steering committee. The final stage is a two-and- half day event with the local winner students of total ca. 40. The performances of the contestants are evaluated by the Industrial and the Technical Committees.	TIE is monitored and the winners of the contest are rewarded by the Industrial Committee; Chairman: Cristian GORDAN, Continental Automotive, Timisoara
			The TIE Plus contest is organized for mainly MSc and PhD students, maybe young industrial engineers. Their registration should be promoted by a University. The total number of the registered contestants is about twenty per year. They should solve a live industrial problem. A set of data required to solve the subject is published on an online platform. This marks the beginning of the "subject solving period" of about two weeks. Each contestant should	

2	TIE PLUS - The Step Towards Interconnect Simulation Technology	Cătălin NEGREA, PhD, Continental Automotive, Timisoara	<p>go through the necessary simulation, design and documentation steps with the goal of delivering a technical solution to the problem. The result should be summarized in a technical report and uploaded for evaluation. If the Industrial and the Technical Committees consider the content is adequate for the final evaluation process, the contestant is required to prepare a short presentation (20-25 min.) that will be exposed to the Committees and a larger audience during an evaluation meeting. If the Industrial and the Technical Committees consider the content is adequate for the final evaluation process, the contestant is required to prepare a short presentation (20-25 min.) that will be exposed to the Committees and a larger audience during an evaluation meeting. After the meeting the winners are announced and awarded.</p>	TIE Plus is monitored and the winners of the contest are rewarded by the Industrial Committee, Chairman: Cosmin Moisă, Continental Automotive, Timisoara, Romania
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3	SIITME - IEEE International Symposium for Design and Technology in Electronic Packaging	Prof. Paul Svasta General Chair, Politehnica University of Bucharest	<p>The IEEE SIITME conference is a powerful and reliable forum, where specialists in the electronics industry come into direct contact with researchers and academics, for the benefit of both parties and with a significant impact on technological development. The particularly important role of this scientific event is to encourage and support the integration of young researchers in the main stream of scientific manifestations. During the conference, many opportunities are created for them to come in contact with distinguished researchers, to expose their ideas in front of an informed audience and to practice and improve their communication and reasoning skills. The number of participants is about 150 per year, of which approx. 60 are young students, researchers or engineers, and the rest are academics and industrial experts. Best and excellent presentations are rewarded with a special focus on rewarding the young presenters. Life-long learning of the participants of all ages is promoted by professional development course and keynote presentations of world-wide recognized experts.</p>	<p>The organization is managed and monitored by the steering Committee. The submitted publications are reviewed and selected by the Publication Committee with the help of the Scientific Committee and international experts, using the Microsoft Conference Management Toolkit. Papers meeting quality criteria are indexed IEEE Xplore Digital Library and Thomson-Reuters ISI-CPCI.</p>
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4	ISSE - International Spring Seminar on Electronics Technology	Olivér Krammer, Associate Professor at Budapest University of Technology and Economics, Secretary of ISSE.	<p>ISSE - a series of annual conferences and a network of electronics packaging education - was founded in 1977 to provide European forum for the exchange of information between senior and junior scientists from academic communities and electronic industries from around the world on topics related to their experimental and theoretical work in the very wide-spread field of electronics and microelectronics technology and packaging.</p> <p>ISSE Network - research fields Thick Films, MCM-D ; Assembly and Joining Assembly and Packaging CAD in Electronics; Ceramic Multichip Modules; Complex Quality Control; Interconnection and Joining; Laser Processing; PCB/MCM Layout Design;</p>	The organization is managed by the Steering Committee with the help of the Technical Program, the Publishing, and the Scientific/Reviewing Committees.
5				

*** Starting date:**

27/10/2021

End date (if applicable):

Key performance indicators

Name of the indicator	Value (only numerical value)	Additional description (if needed)
<p>Number of representatives of the target group who take part in up-/re-skilling (per year)</p>	<p>TIE: number of participants >300 students/year TIE Plus: number of participants >20 young researcher-engineers/year SIITME: number of participants >120, including more than 50 students ISSE: More than 150 participants, ca half of them students or young scientists.</p>	<p>TIE: number of participants >300 students/year TIE Plus: number of participants >20 young researcher-engineers/year SIITME: number of participants >120, including more than 50 students ISSE: More than 150 participants, ca half of them students or young scientists.</p>
<p>Others</p>	<p>TIE: The score limit for the finalist students, on the basis of which they receive a qualified certificate of achievement, and the bests receive awards. Actual score limits are set annually by the Technical Committee. TIE Plus: Score limits are determined for the contestants, based on which they may receive qualified certificates of achievement. The bests can receive various awards, cash prizes, and occasionally job offers from the Awards Committee formed by industry professionals. The actual awards and the score limits are determined jointly by the Technical Committee and the Award Committee on an annual basis. SIITME & ISSE: As a recognition of the achievements of the participants, papers meeting quality criteria are included into the indexed IEEE Xplore Digital Library and Thomson-Reuters ISI-CPCI. In addition, the best and excellent presentations/posters are rewarded, with a special attention on rewarding the young presenters.</p>	<p>TIE: The score limit for the finalist students, on the basis of which they receive a qualified certificate of achievement, and the bests receive awards. Actual score limits are set annually by the Technical Committee. TIE Plus: Score limits are determined for the contestants, based on which they may receive qualified certificates of achievement. The bests can receive various awards, cash prizes, and occasionally job offers from the Awards Committee formed by industry professionals. The actual awards and the score limits are determined jointly by the Technical Committee and the Award Committee on an annual basis. SIITME & ISSE: As a recognition of the achievements of the participants, papers meeting quality criteria are included into the indexed IEEE Xplore Digital Library and Thomson-Reuters ISI-CPCI. In addition, the best and excellent presentations/posters are rewarded, with a special attention on rewarding the young presenters.</p>

I agree to provide updates on activities related to this commitment, in the regular annual survey on Pact for Skills. If there is no participation in the survey, the commitment will be considered to be inactive.

I confirm I have agreement of all partners to represent them in the Pact for Skills.

I accept the privacy statement presented below.

Privacy statement

[Privacy_statement.pdf](#)

Thank you

Please do not change information below

Status of the application

- Accepted
- Under revision
- Suspended
- Rejected

Reason for suspension/rejection

Contact

[Contact Form](#)